IXYS

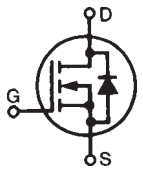
HiperFET™ Power MOSFETs

IXFK180N10
IXFX180N10

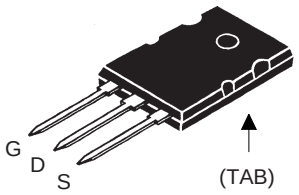
V_{DSS} = 100V
I_{D25} = 180A
$R_{DS(on)}$ ≤ 8mΩ

Single MOSFET Die

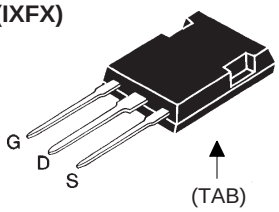
N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



TO-264 (IXFK)



PLUS247 (IXFX)



G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	100	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	100	V
V_{GSS}	Continuous	±20	V
V_{GSM}	Transient	±30	V
I_{D25}	T_C = 25°C (Chip Capabitlty)	180	A
I_{LRMS}	Leads Current Limit, RMS	160	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	720	A
I_A	T_C = 25°C	180	A
E_{AS}	T_C = 25°C	3	J
dV/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	5	V/ns
P_D	T_C = 25°C	560	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	1.6mm (0.062 in.) from Case for 10s	300	°C
T_{SOLD}	Plastic Body for 10s	260	°C
M_d	Mounting Force (PLUS247)	20..120/4.5..27	N/lb.
	MountingTorque (TO-264)	1.13/10	Nm/lb.in.
Weight	PLUS247	6	g
	TO-264	10	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 3mA	100			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 8mA	2.0		4.0	V
I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V			±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$			100	μA
	V_{GS} = 0V, T_J = 125°C			2	mA
$R_{DS(on)}$	V_{GS} = 10V, $I_D = 0.5 \bullet I_{D25}$, Note 1			8	mΩ

Features

- International Standard Packages
- High Current Handling Capability
- Avalanche Rated
- Low $R_{DS(on)}$ HDMOS™ Process
- Fast intrinsic diode
- Low Package Inductance

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- DC-DC Converters
- Battery Chargers
- Switched-Mode and Resonant-Mode Power Supplies
- DC Choppers
- AC Motor Drives
- Temperature and Lighting Controls

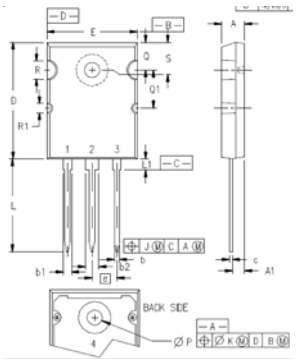
Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 10V, I_D = 60A, Note 1	45	76		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		10.90		nF
C_{oss}			3.55		nF
C_{rss}			1.94		nF
$t_{d(on)}$	**Resistive Switching Times**		50		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		90		ns
$t_{d(off)}$	R_G = 1Ω (External)		140		ns
t_f			65		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		390		nC
Q_{gs}			55		nC
Q_{gd}			195		nC
R_{thJC}				0.22	°C/W
R_{thCS}			0.15		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			180	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			720	A
V_{SD}	I_F = 100A, V_{GS} = 0V, Note 1			1.5	V
t_{rr}	I_F = 90A, -di/dt = 100A/μs			250	ns
Q_{RM}	V_R = 50V, V_{GS} = 0V		1.1		μC
I_{RM}			13		A

Note 1: Pulse Test, t ≤ 300μs; Duty Cycle, d ≤ 2%.

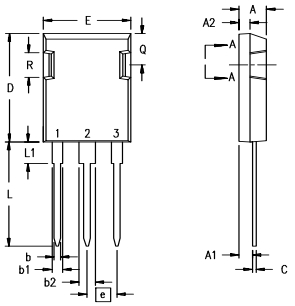
TO-264 (IXFK) Outline



1 – GATE
2, 4 – DRAIN (COLLECTOR)
3 – SOURCE (EMITTER)

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.185	.209	4.70	5.31
A1	.102	.118	2.59	3.00
b	.037	.055	0.94	1.40
b1	.087	.102	2.21	2.59
b2	.110	.126	2.79	3.20
c	.017	.029	0.43	0.74
D	1.007	1.047	25.58	26.59
E	.760	.799	19.30	20.29
e	.215BSC		5.46 BSC	
J	.000	.010	0.00	0.25
K	.000	.010	0.00	0.25
L	.779	.842	19.79	21.39
L1	.087	.102	2.21	2.59
ØP	.122	.138	3.10	3.51
Q	.240	.256	6.10	6.50
Q1	.330	.346	8.38	8.79
ØR	.155	.187	3.94	4.75
ØR1	.085	.093	2.16	2.36
S	.243	.253	6.17	6.43

PLUS 247™ (IXFX) Outline



Terminals: 1 - Gate
2 - Drain (Collector)
3 - Source (Emitter)
4 - Drain (Collector)

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.83	5.21	.190	.205
A_1	2.29	2.54	.090	.100
A_2	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b_1	1.91	2.13	.075	.084
b_2	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45 BSC		.215 BSC	
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	0.244
R	4.32	4.83	.170	.190

Fig. 1. Output Characteristics @ 25ºC

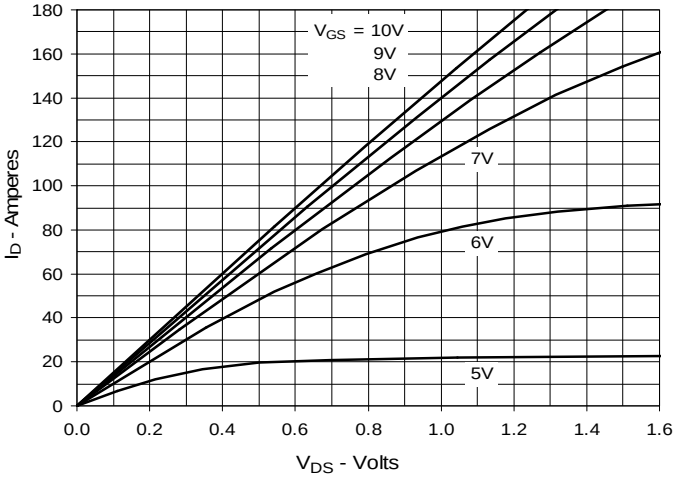


Fig. 2. Extended Output Characteristics @ 25ºC

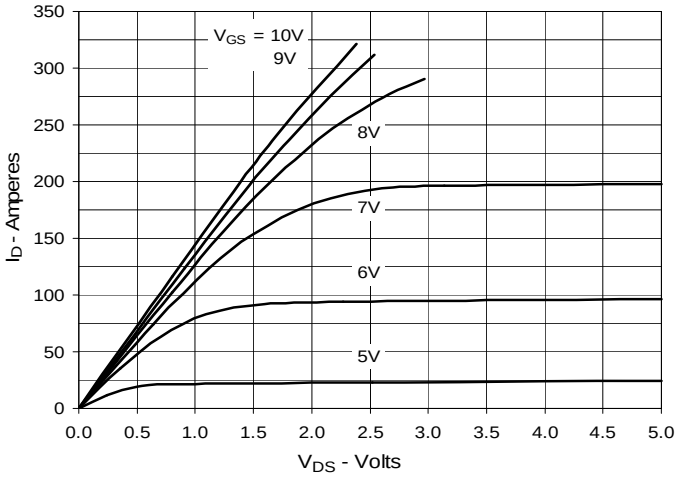


Fig. 3. Output Characteristics @ 125ºC

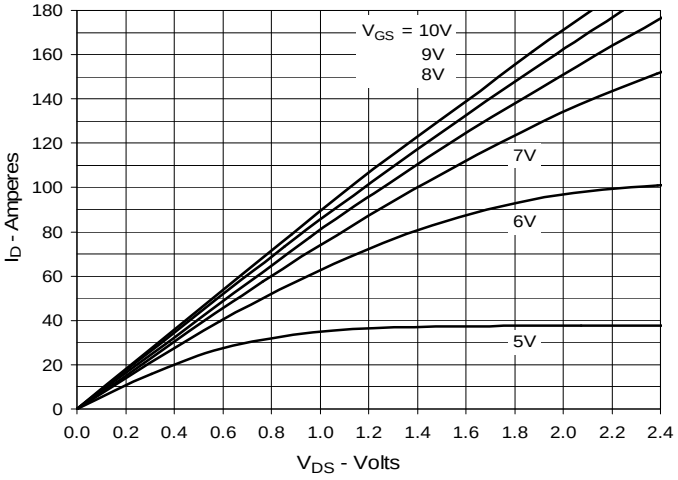


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 90A Value vs. Junction Temperature

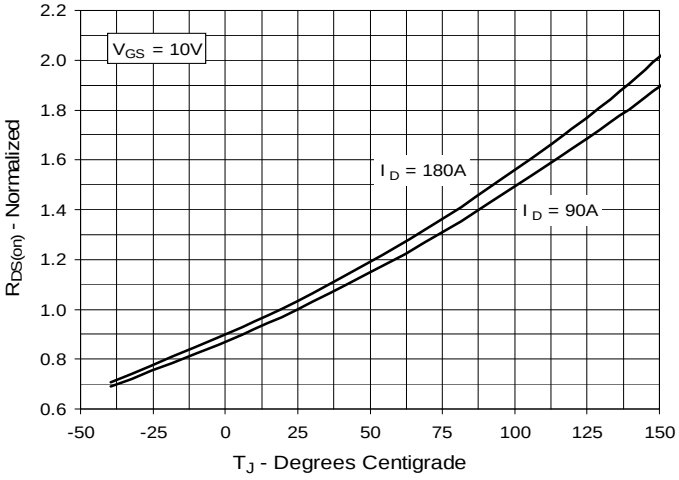


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 90A Value vs. Drain Current

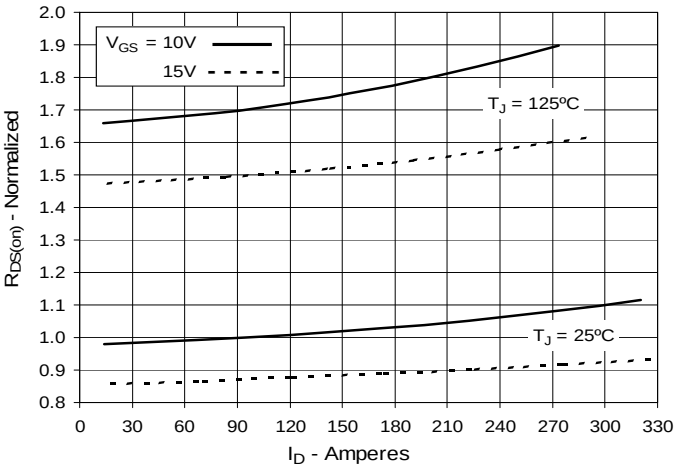


Fig. 6. Maximum Drain Current vs. Case Temperature

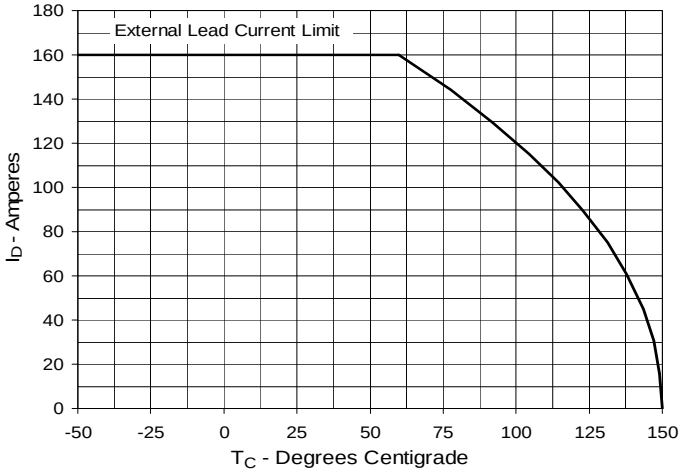


Fig. 7. Input Admittance

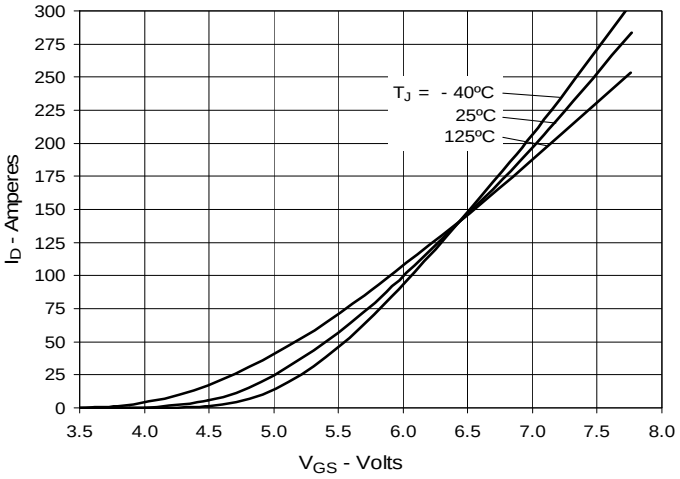


Fig. 8. Transconductance

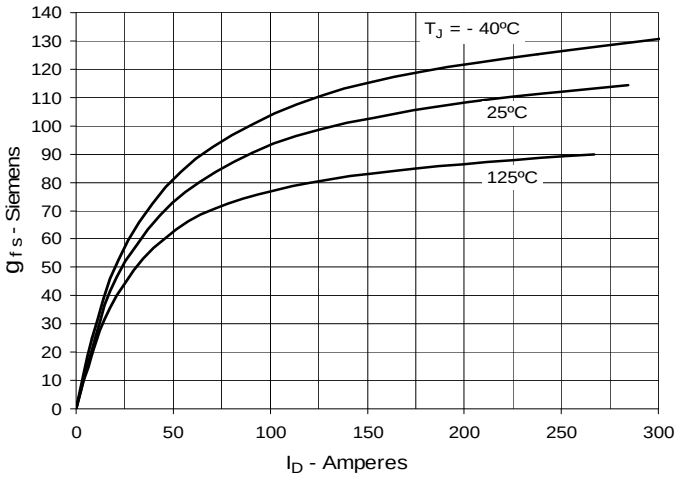


Fig. 9. Forward Voltage Drop of Intrinsic Diode

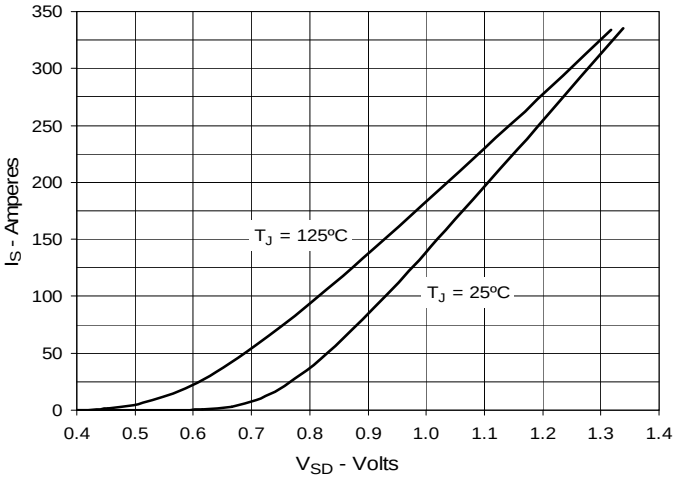


Fig. 10. Gate Charge

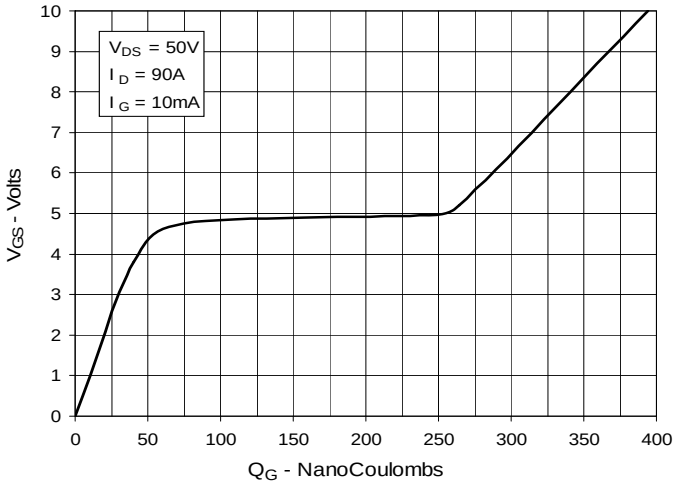


Fig. 11. Capacitance

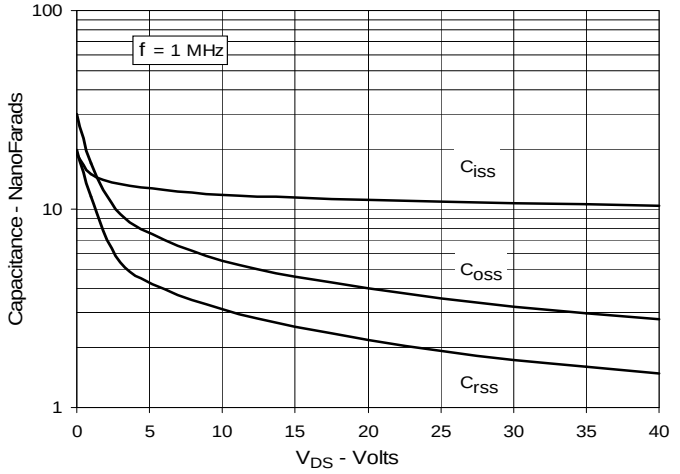


Fig. 12. Maximum Transient Thermal Impedance

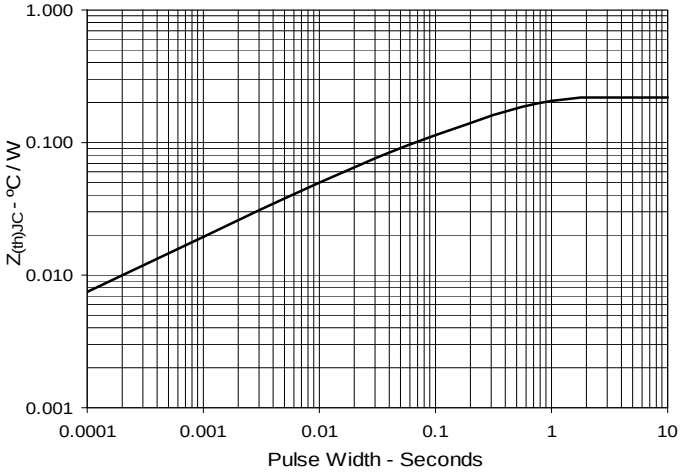


Fig. 13. Forward-Bias Safe Operating Area @ T_C = 25ºC

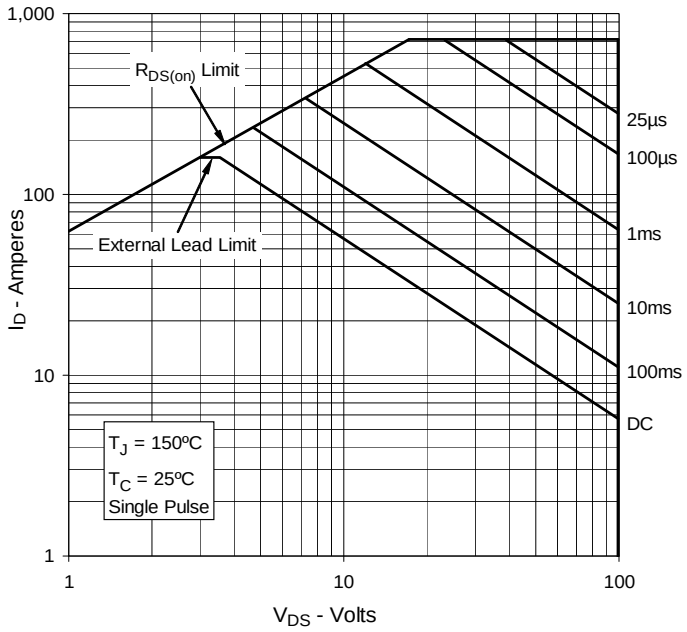


Fig. 14. Forward-Bias Safe Operating Area @ T_C = 75ºC